

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-17. (canceled)

18. (previously presented) A method as in claim 24 wherein step (b) advances curing of the thermosetting resin.

19 and 20. (canceled)

21. (previously presented) A method as in claim 24 wherein the semiconductor device comprises an integrated circuit.

22. (previously presented) A method as in claim 24 wherein step (a) includes a transfer molding process.

23. (previously presented) A method as in claim 24 wherein step (a) includes a potting process.

24. (Currently amended) A method of making a semiconductor device to be soldered with an Sn-Ag-Cu type solder to a substrate, the method comprising:

(a) sealing the semiconductor device in a package by surrounding it with thermosetting resin and thermally curing the resin at a first temperature;

(b) baking the thermosetting resin at a second temperature not higher than the first temperature;

(c) further baking the thermosetting resin at a third temperature higher than the first temperature, wherein the third temperature is between about 220°C and about 260°C; and

(d) inspecting the semiconductor device.

1 25. (previously presented) A method as in claim 24 wherein a conductive lead
2 is adhesively affixed to a main surface of the semiconductor device.

1 26. (previously presented) A method as in claim 25 wherein the conductive
2 lead is adhesively affixed to a peripheral portion of the main surface of the semiconductor
3 device.

1 27. (previously presented) A method as in claim 26 wherein an electrode of
2 the semiconductor device is electrically connected to the conductive lead.

28-30. (canceled)